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Article and system claims 28-58 and 59-123 are considered to be appropriately examined together at this time. It is also believed that method claims 123-151 can be examined together with the other pending claims without undue burden, particularly in view of the search and examination completed in parent application 09/312,045. Consideration of all claims presented at this time is earnestly solicited.

Applicants also enclose a copy of the Information Disclosure Statement filed on June 27, 2002.

Early consideration and allowance of the application are earnestly solicited.

Respectfully submitted,



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VERSION WITH CHANGES MARKED

28. (amended) An article of manufacture comprising:
a semiconductor wafer substrate having one or more microvias that have an aspect ratio of at least about 4:1 and a diameter of about 200 nm or less,
one or more microvias containing therein an electrolytic copper deposit obtained from an electroplating composition that comprises at least one soluble copper salt, an electrolyte, and one or more brightener compounds having a molecular weight of about 1000 or less and that are present in a concentration of at least about 1.5 mg per liter [of the electroplating] of the electroplating composition.

51. (amended) An article of manufacture comprising:
a semiconductor wafer substrate having one or more microvias that have an aspect ratio of at least about 4:1 and a diameter of about 200 nm or less,
one or more microvias containing therein an electrolytic copper deposit obtained from an electroplating composition that comprises at least one soluble copper salt, an electrolyte, and one or more brightener compounds having a molecular weight of about 1000 or less and that are present in a concentration of at least about 1.5 mg per liter [of the electroplating] of the electroplating composition.